


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ADG/20/12232	
1.3 Title of PCI	Orientation of PowerFLATTM 8X8 HV Package in carrier tape & Datasheet update	
1.4 Product Category	Power MOSFET	
1.5 Issue date	2020-06-30	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE
2.1.2 Marketing Manager	Anna MOTTESE
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	ASE-WEIHAI (China) and CARSEM (Malaysia)

4. Description of change

	Old	New
4.1 Description	PowerFLATTM 8X8 HV packed in carrier tape with reference to the pin positioned at the top left.	PowerFLATTM 8X8 HV packed in carrier tape with reference to the pin positioned at the top right.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	in order to be aligned to the JEDEC/EIA specification.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	by Q.A. number
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7. Timing / schedule

7.1 Date of qualification results	2020-06-29
7.2 Intended start of delivery	2020-07-29
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

12232 Public product.pdf
12232 Orientation of PowerFLATTM 8X8 HV in carrier tape.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
2729678	STL36N55M5	

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